# BTA41 A/B BTB41 B

# STANDARD TRIACS

#### **FEATURES**

■ HIGH SURGE CURRENT CAPABILITY

■ COMMUTATION: (dV/dt)c>10V/µs

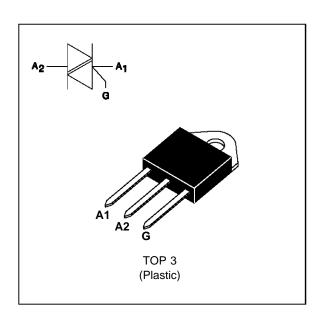
■ BTA Family :

INSULATING VOLTAGE = 2500V<sub>(RMS)</sub>

(UL RECOGNIZED: E81734)

#### **DESCRIPTION**

The BTA41 A/B / BTB41 B triac family are high performance glass passivated PNPN devices. These parts are suitables for general purpose applications where high surge current capability is required. Application such as phase control and static switching on inductive or resistive load.



# **ABSOLUTE RATINGS** (limiting values)

Symbol	Parameter	Value	Unit		
I <sub>T(RMS)</sub>	RMS on-state current	ВТА	Tc = 75 °C	40	Α
	(360° conduction angle)	втв	Tc = 85 °C	45	
ITSM	1 - 1			315	Α
	( Tj initial = 25°C )			300	
l <sup>2</sup> t	I2t value	tp = 10 ms	450	A <sup>2</sup> s	
dl/dt	Critical rate of rise of on-state current Gate supply: IG = 500mA dig/dt = 1A/µ	Repetitive F = 50 Hz	10	A/μs	
		50			
Tstg Tj	Storage and operating junction temperature range			- 40 to + 150 - 40 to + 125	°C °C
TI	Maximum lead temperature for soldering during 10 s at 4.5 mm from case			260	°C

Symbol	Parameter	BTA41A/B / BTB41 B				Unit
		400	600	700	800	
VDRM VRRM	Repetitive peak off-state voltage Tj = 125 °C	400	600	700	800	V

March 1995 1/5

# BTA41 A/B / BTB41 B

# THERMAL RESISTANCES

Symbol	Parameter	Value	Unit	
Rth (j-a)	Junction to ambient	50	°C/W	
Rth (j-c) DC	Junction to case for DC BTA		1.2	°C/W
		втв	0.8	
Rth (j-c) AC	Junction to case for 360° conduction angle	ВТА	0.9	°C/W
	( F= 50 Hz)		0.6	

# **GATE CHARACTERISTICS** (maximum values)

 $PG~(AV) = 1W~~PGM = 40W~(tp = 20~\mu s)~~IGM = 8A~(tp = 20~\mu s)~~V_{GM} = 16V~(tp = 20~\mu s).$ 

# **ELECTRICAL CHARACTERISTICS**

Symbol	Test Conditions		Quadrant	Quadrant		Suffix	
					Α	В	
IGT	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	Tj=25°C	1-11-111	MAX	100	50	mA
			IV	MAX	150	100	
VGT	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	Tj=25°C	I-II-III-IV	MAX	1.5		V
VGD	VD=VDRM RL=3.3kΩ	Tj=125°C	I-II-III-IV	MIN	0.2		V
tgt	$V_D=V_DRM$ $I_G=500mA$ $dI_G/dt=3A/\mu s$	Tj=25°C	I-II-III-IV	TYP	2.5		μs
IL	I <sub>G</sub> =1.2 I <sub>G</sub> T	Tj=25°C	I-III-IV	TYP	70	60	mA
			II		200	180	
IH *	I <sub>T</sub> = 500mA gate open	Tj=25°C		MAX	100	80	mA
V <sub>TM</sub> *	I <sub>TM</sub> = 60A tp= 380μs	Tj=25°C		MAX	1.	.8	V
IDRM	V <sub>DRM</sub> Rated	Tj=25°C		MAX	0.01		mA
IRRM	VRRM Rated	Tj=125°C		MAX	(	6	
dV/dt *	Linear slope up to V <sub>D</sub> =67%V <sub>DRM</sub> gate open	Tj=125°C		MIN	250	250	V/μs
(dV/dt)c *	(dl/dt)c = 18A/ms BTA (dl/dt)c = 20A/ms BTB	Tj=125°C		MIN	10		V/μs

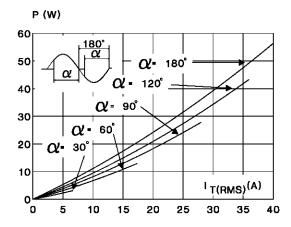
<sup>\*</sup> For either polarity of electrode A2 voltage with reference to electrode A1.

#### **ORDERING INFORMATION**

Package	IT(RMS)	V <sub>DRM</sub> / V <sub>RRM</sub>	Sensitivity S	Specification
	Α	V	Α	В
ВТА	41	400	Χ	X
(Insulated)		600	X	X
		700	X	X
		800	Χ	X
втв	45	400		X
(Uninsulated)		600		X
		700		Х
		800		Х

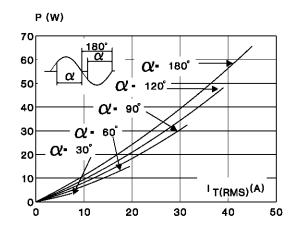
 $\label{eq:Fig.1} \textbf{Fig.1:} \ \, \text{Maximum RMS power dissipation versus RMS} \\ \text{on-state current (F=50Hz)}.$ 

(Curves are cut off by (dl/dt)c limitation) (BTA)

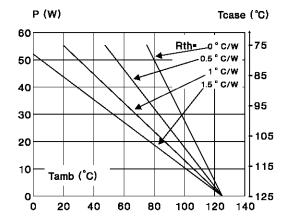


 $\label{eq:Fig.3:Maximum RMS power dissipation versus RMS on-state current (F=50Hz).}$ 

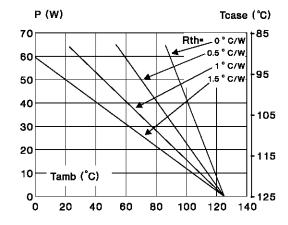
(Curves are cut off by (dl/dt)c limitation) (BTB)



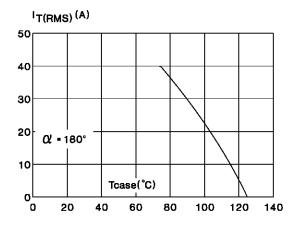
**Fig.2**: Correlation between maximum RMS power dissipation and maximum allowable temperatures ( $T_{amb}$  and  $T_{case}$ ) for different thermal resistances heatsink + contact (BTA).



**Fig.4**: Correlation between maximum RMS power dissipation and maximum allowable temperatures ( $T_{amb}$  and  $T_{case}$ ) for different thermal resistances heatsink + contact (BTB).



**Fig.5**: RMS on-state current versus case temperature. (BTA)



**Fig.7**: Relative variation of thermal transient impedance pulse duration.

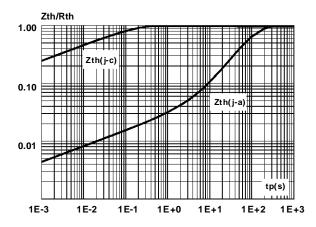
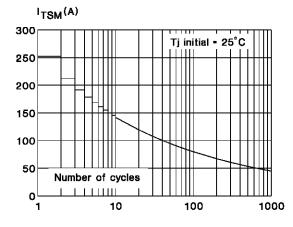
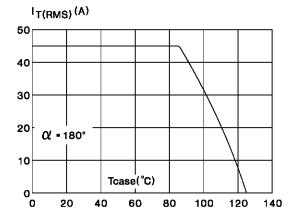


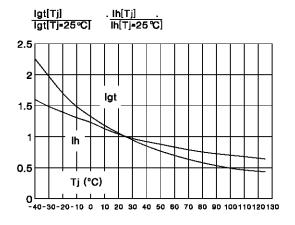
Fig.9 : Non Repetitive surge peak on-state current versus number of cycles.



**Fig.6**: RMS on-state current versus case temperature. (BTB)



**Fig.8 :** Relative variation of gate trigger current and holding current versus junction temperature.



**Fig.10**: Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \le 10ms$ , and corresponding value of  $l^2t$ .

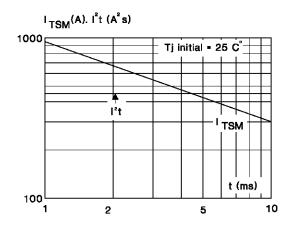
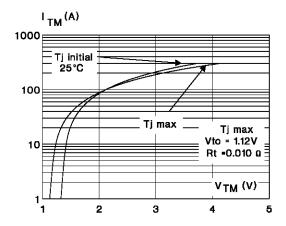
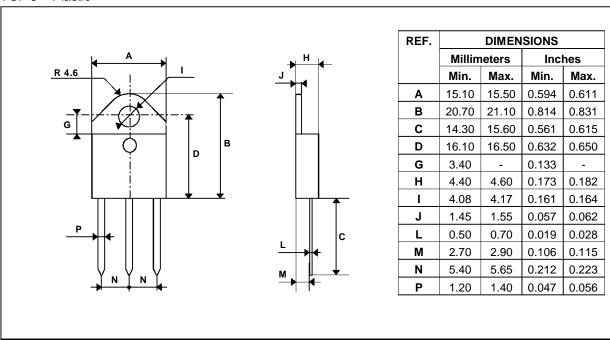


Fig.11: On-state characteristics (maximum values).



#### **PACKAGE MECHANICAL DATA**

TOP 3 Plastic



Cooling method : C Marking : type number

Weight: 4.7 g

Recommended torque value : 0.8 m.N. Maximum torqur value : 1 m.N.

Information furnished is believed to be accurate and reliable. However, SGS-THOMSON Microelectronics assumes no responsability for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of SGS-THOMSON Microelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied.

SGS-THOMSON Microelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of SGS-THOMSON Microelectronics.

© 1995 SGS-THOMSON Microelectronics - Printed in Italy - All rights reserved.

#### SGS-THOMSON Microelectronics GROUP OF COMPANIES

Australia - Brazil - France - Germany - Hong Kong - Italy - Japan - Korea - Malaysia - Malta - Morocco - The Netherlands - Singapore - Spain - Sweden - Switzerland - Taiwan - Thailand - United Kingdom - U.S.A.

